Mini ITX Motherboard Based on Intel H310C Chipset, Supporting Intel® Skylake-S, Kabylake-S, Coffee Lake-S LGA1151 Series CPU



Main Features:

- · Support Intel® 6th/7th/8th/9th Gen. LGA1151 series CPU
- · DDR4 SO-DIMM memory
- · Support dual Gigabit network and 4G/5G module
- · Support up to 6 x COM
- · Suitable for smart cities, smart medical care, intelligent industrial control, etc.

Description:

EMB-IH310D-MI26 utilizes Intel H310C chipset and supports Intel 6th Gen. Skylake, 7th Gen. Kabylake-S, 8th/9th Gen. Coffee Lake-S series processors. It comes with built-in LVDS display output, and supports up to 6 x COM-RS232 ports and 2 x Gigabit network. It can be applied to new retail, smart education, smart medical care, industrial automation, intelligent control, machine vision, electric power and energy and other application fields.

Specification:

СРИ	СРИ	Support Intel® Skylake-S, Kabylake-S, Coffee Lake-S LGA1151 Series CPU
	Chipset	Intel® H310C Chipset
Memory	Туре	SO-DIMM DDR4
	Max. Capacity	16GB
Storage	M.2 2280	1 x M.2 2280, supports SATA/PCIe SSD (DIP switch for selection)
	SATA	1 x SATA3.0 standard interface
Software	Wake on LAN	Support
	OS	Windows 8.1/10, Linux
Display	Graphics	CPU integrated GPU
	Display Output	HDMI1.4 (Max. 3840 x 2160@30Hz)
		VGA & HDMI1.4 (VGA Max. 1920 x 1080)
		LVDS (Max. 1920 x 1080@60Hz dual-channel 8bit 24B)
Audio	Controller	Realtek ALC671
	Interfaces	1 x Audio OUT, 1 x Mic IN
		Support 8Ω 3W Speaker

Controller	2 x RTL8111H Gigabit Network, supports Wake on LAN and PXE
External	2 x USB 3.0
Built-in	6 x USB 2.0
СОМ	Up to 6 x COM-RS232 (COM2 and COM6 can be set as
	RS232/RS485 via jumper selection)
M.2	1 x M.2 2230, supports WIFI/BT
	1 x M.23042/52, supports 4G/5G (Nano SIM Card)
Interfaces	12/19V DC IN
	ATX 4pin Jack
Operating Temp.	0°C~60°C
Storage Temp.	-20℃-80℃
Dimension	170 x 170mm
Cooling	Standard cooling
	External Built-in COM M.2 Interfaces Operating Temp. Storage Temp. Dimension

I/O Interfaces:



